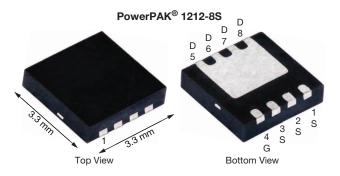




P-Channel 30 V (D-S) MOSFET

PRODU	PRODUCT SUMMARY					
V _{DS} (V)	R _{DS(on)} (Ω) MAX.	I _D (A)	Q _g (TYP.)			
	0.0056 at V _{GS} = -10 V	-50 ^e				
-30	0.0070 at V _{GS} = -6 V	-50 e	45 nC			
	0.0090 at V _{GS} = -4.5 V	-50 ^e				



Ordering Information:

SiSS27DN-T1-GE3 (Lead (Pb)-free and Halogen-free)

FEATURES

- TrenchFET® Power MOSFET
- Low thermal resistance PowerPAK® package with small size and low 0.75 mm profile



 Material categorization: For definitions of compliance please see www.vishay.com/doc?99912

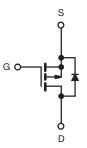
RoHS

HALOGEN

FREE

APPLICATIONS

- Notebook computers and mobile computing
 - Adaptor switch
 - Load switch
 - DC/DC converter
 - Power management



P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (TA =	= 25 °C, unless other	wise noted)		
PARAMETER		SYMBOL	LIMIT	UNIT
Drain-Source Voltage		V _{DS}	-30	V
Gate-Source Voltage		V _{GS}	± 20	V
	T _C = 25 °C		-50 e	
Continuous Drain Comment (T. 150 °C)	T _C = 70 °C		-50 e	
Continuous Drain Current (T _J = 150 °C)	T _A = 25 °C	I _D	-23 ^{a,b}	
	T _A = 70 °C		-18.5 ^{a,b}	
Pulsed Drain Current (t = 100 μs)		I _{DM}	-200	A
Continuous Source-Drain Diode Current	T _C = 25 °C		-47.5	
Continuous Source-Drain Diode Current	T _A = 25 °C	ls	-4 a,b	
Avalanche Current	$T_{C} = 70 ^{\circ}\text{C}$ $T_{A} = 25 ^{\circ}\text{C}$ $T_{A} = 70 ^{\circ}\text{C}$ $T_{C} = 25 ^{\circ}\text{C}$ $T_{A} = 25 ^{\circ}\text{C}$ $L = 0.1 \text{mH}$ $T_{C} = 25 ^{\circ}\text{C}$ $T_{C} = 70 ^{\circ}\text{C}$	I _{AS}	-25	
Single-Pulse Avalanche Energy	L = U. I IIIII	E _{AS}	31	mJ
	T _C = 25 °C		57	
Maximum Daway Dissination	T _C = 70 °C		36	w
Maximum Power Dissipation	T _A = 25 °C	P _D	4.8 ^{a,b}	VV
	T _A = 70 °C		3 a,b	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	-50 to 150	°C
Soldering Recommendations (Peak Temperature) c,d			260	

Notes

- a. Surface mounted on 1" x 1" FR4 board.
- b. t = 10 s.
- c. See solder profile (<u>www.vishay.com/doc?73257</u>). The PowerPAK 1212-8S is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- d. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.
- e. Package limited.

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THERMAL RESISTANCE RATING	S				
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT
Maximum Junction-to-Ambient a,b	t ≤ 10 s	R_{thJA}	21	26	°C/W
Maximum Junction-to-Case (Drain)	Steady State	R_{thJC}	1.7	2.2	G/ VV

Notes

- a. Surface mounted on 1" x 1" FR4 board.
- b. Maximum under steady state conditions is 63 °C/W.

PARAMETER	unless otherwise noted) SYMBOL TEST CONDITIONS			TYP.	MAX.	UNIT
Static	STWIDOL	TEST CONDITIONS	MIN.	1115.	IVIAA.	ONIT
Drain-Source Breakdown Voltage	V_{DS}	V _{GS} = 0 V, I _D = - 250 μA	-30	l -	_	V
V _{DS} Temperature Coefficient	ΔV _{DS} /T _J	VGS = 0 V, ID = 200 μA	-	-22	_	v
		I _D = -250 μA				mV/°C
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$		-	5.7	-	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$	-1	-	-2.2	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$	-	-	± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}$	-	-	-1	μA
	.033	$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 \text{ °C}$	-	-	-10	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le -5 \text{ V}, V_{GS} = -10 \text{ V}$	-20	-	-	Α
		$V_{GS} = -10 \text{ V}, I_D = -15 \text{ A}$	-	0.0046	0.0056	
Drain-Source On-State Resistance a	R _{DS(on)}	$V_{GS} = -6 \text{ V}, I_D = -10 \text{ A}$	-	0.0058	0.0070	Ω
		$V_{GS} = -4.5 \text{ V}, I_D = -5 \text{ A}$	-	0.0073	0.0090	
Forward Transconductance ^a	9 _{fs}	$V_{DS} = -15 \text{ V}, I_{D} = -15 \text{ A}$	-	52	-	S
Dynamic ^b						
Input Capacitance	C _{iss}		-	5250	-	pF
Output Capacitance	Coss	$V_{DS} = -15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	ı	530	-	
Reverse Transfer Capacitance	C_{rss}		1	485	-	
Tabal Oaks Observe	Q _g	$V_{DS} = -15 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -20 \text{ A}$	-	92	140	nC
Total Gate Charge			-	45	70	
Gate-Source Charge		$V_{DS} = -15 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -20 \text{ A}$	-	15	-	
Gate-Drain Charge	Q _{gd}		-	16	-	
Gate Resistance	R _q	f = 1 MHz	0.6	3	6	Ω
Turn-On Delay Time	t _{d(on)}		-	60	120	
Rise Time	t _r	$V_{DD} = -15 \text{ V}, R_1 = 1.5 \Omega$	-	45	90	
Turn-Off DelayTime	t _{d(off)}	$I_D \cong -10 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_g = 1 \Omega$	-	50	100	ns
Fall Time	t _f	1	-	20	40	
Turn-On Delay Time	t _{d(on)}		-	16	30	
Rise Time	t _r	$V_{DD} = -15 \text{ V}, R_1 = 1.5 \Omega$	-	5	10	
Turn-Off DelayTime	t _{d(off)}	$t_{d(off)}$ $I_D \cong -10 \text{ A}, V_{GEN} = -10 \text{ V}, R_g = 1 \Omega$		65	130	
Fall Time	t _f	1	-	10	20	1
Drain-Source Body Diode Characterist						
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C	-	-	-50 ^c	
Pulse Diode Forward Current d	I _{SM}		-	-	-200	Α
Body Diode Voltage	V _{SD}	I _F = -10 A	-	-0.8	-1.2	V
Body Diode Reverse Recovery Time	t _{rr}	1 - 2	-	30	60	ns
Body Diode Reverse Recovery Charge	Q _{rr}	1	-	21	40	nC
Reverse Recovery Fall Time	t _a			16	-	
Reverse Recovery Rise Time	t _b	-		14		ns

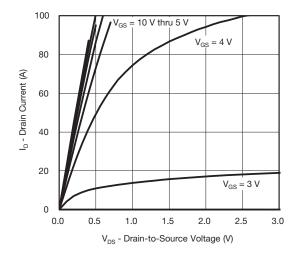
Notes

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Package limited.
- d. $t = 100 \, \mu s$.

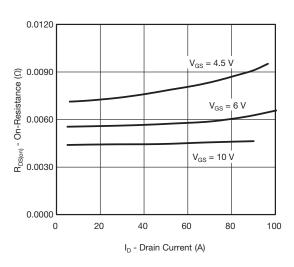
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



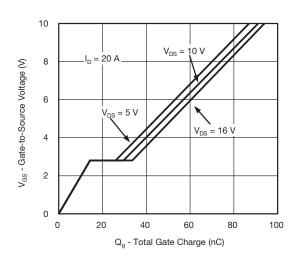
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



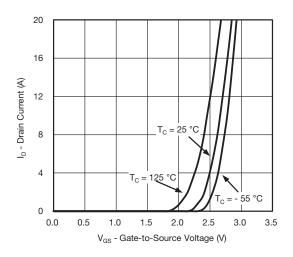
Output Characteristics



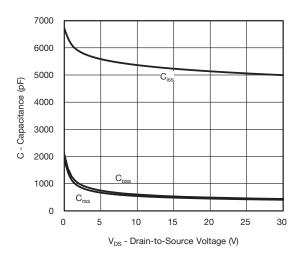
On-Resistance vs. Drain Current and Gate Voltage



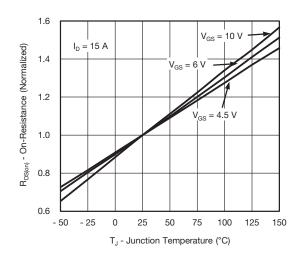
Gate Charge



Transfer Characteristics



Capacitance



On-Resistance vs. Junction Temperature

 $I_D = 15 A$

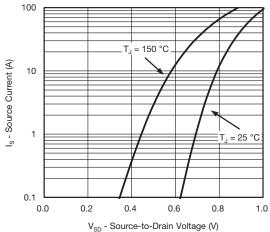
 $T_J = 125 \, ^{\circ}C$

8

10



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Source-Drain Diode Forward Voltage

V) V_{GS} - Gate-to-Source Voltage (V)

2

4

On-Resistance vs. Gate-to-Source Voltage

6

0.020

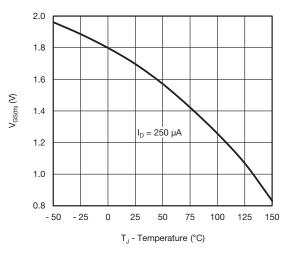
0.016

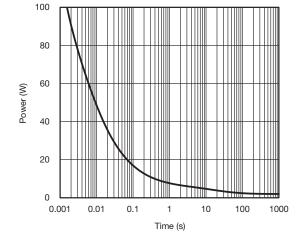
On-Resistance (Ω) 0.012

0.004

0.000

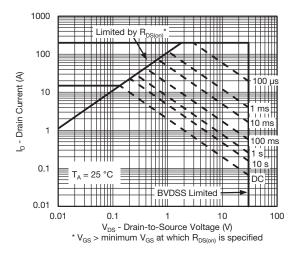
0





Threshold Voltage

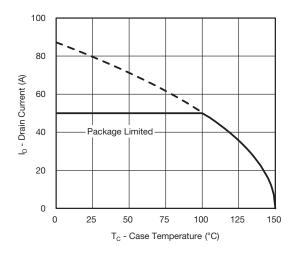
Single Pulse Power, Junction-to-Ambient

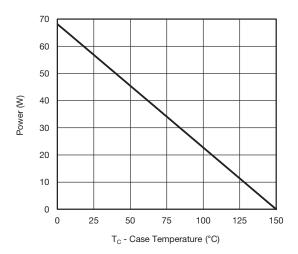


Safe Operating Area, Junction-to-Ambient



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)





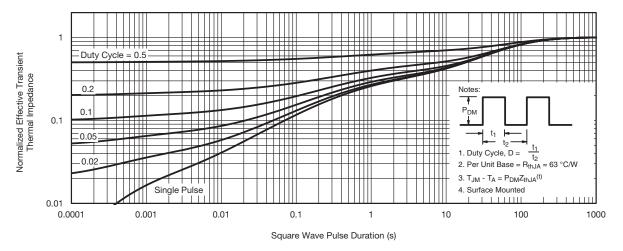
Current Derating*

Power, Junction-to-Case

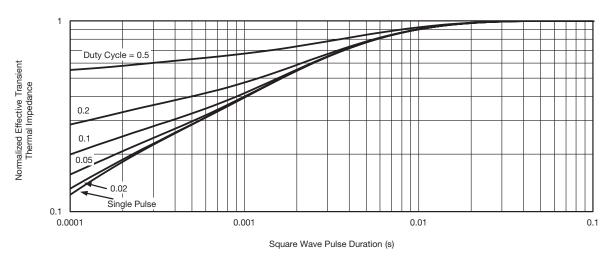
^{*} The power dissipation P_D is based on $T_{J(max.)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient

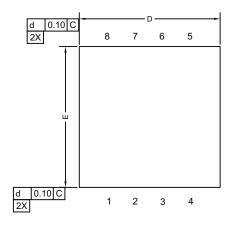


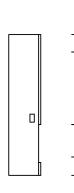
Normalized Thermal Transient Impedance, Junction-to-Case

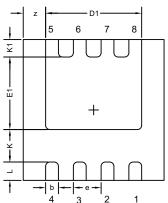
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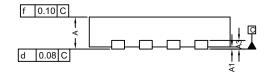


Case Outline for PowerPAK® 1212-8S









DIM.	MILLIMETERS			INCHES				
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.		
Α	0.67	0.75	0.83	0.027	0.030	0.033		
A1	0	-	0.05	0	-	0.002		
А3		0.20 REF			0.008 REF			
b		0.30 BSC		0.012 BSC				
D		3.30 BSC			3.30 BSC 0.130 BSC			
D1	2.15	2.25	2.35	0.084	0.088	0.092		
E		3.30 BSC			0.130 BSC			
E1	1.60	1.70	1.80	0.063	0.067	0.071		
е		0.65 BSC		0.026 BSC				
K		0.76 TYP		0.030 TYP				
K1		0.41 TYP		0.016 TYP				
L	0.43 BSC		0.017 BSC					
Z		0.525 TYP		0.021 TYP				

DWG: 6008

Note

• Millimeters will govern.



RECOMMENDED MINIMUM PADS FOR PowerPAK® 1212-8 Single



Recommended Minimum Pads Dimensions in Inches/(mm)

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APPLICATION NOTE



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